



SOT1660-2

HLQFP156, plastic, thermal enhanced low profile quad flat package; 156 terminals; 0.4 mm pitch; 14 mm x 20 mm x 1.4 mm body

5 November 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP156
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-10-2018
Manufacturer package code	98ASA01028D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	20	-	mm
package width	-	14	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	156	-	



HLQFP156, plastic, thermal enhanced low profile quad flat package; 156 terminals; 0.4 mm pitch; 14 mm x 20 mm x 1.4 mm body

2 Package outline

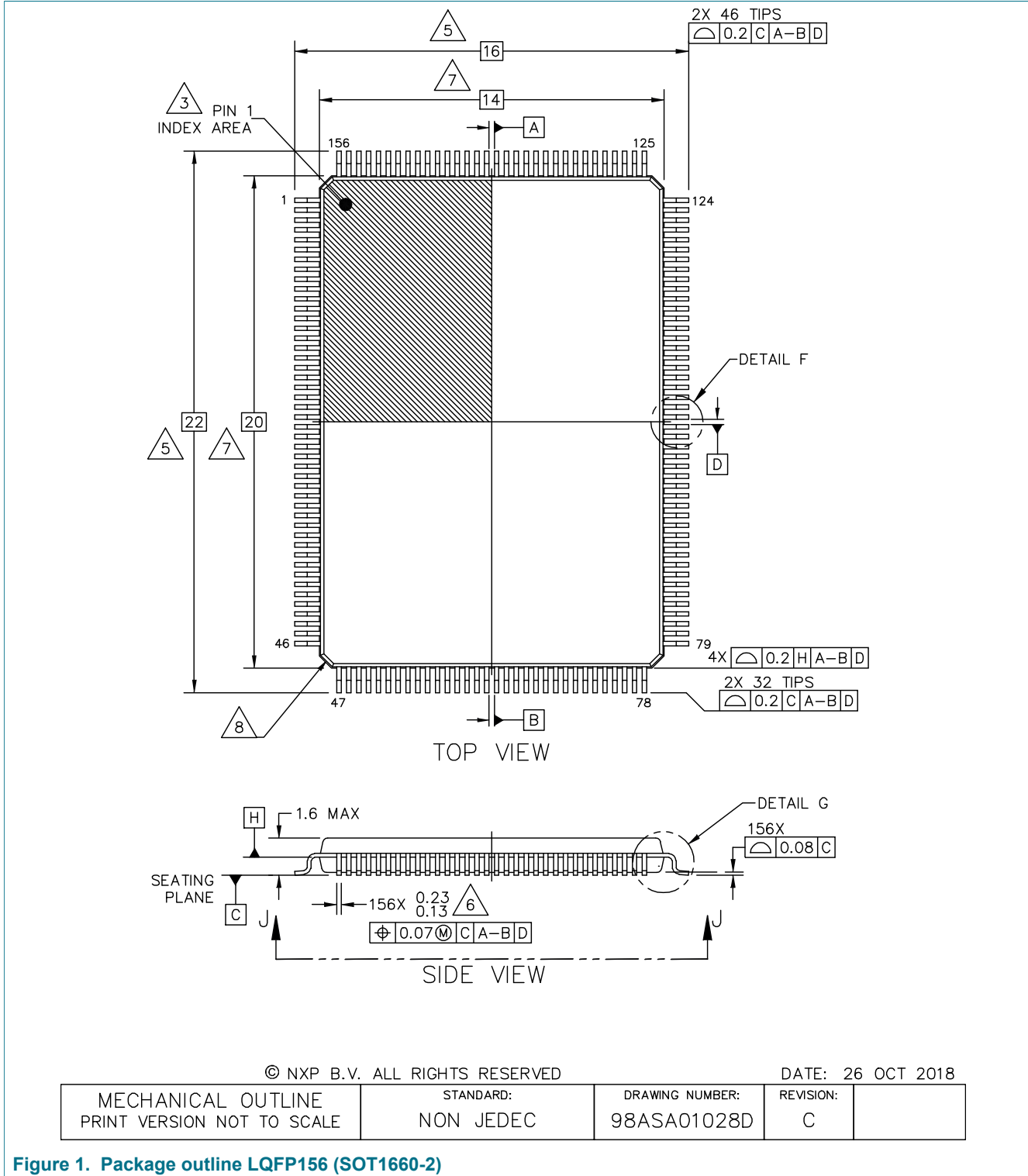


Figure 1. Package outline LQFP156 (SOT1660-2)

HLQFP156, plastic, thermal enhanced low profile quad flat package; 156 terminals; 0.4 mm pitch; 14 mm x 20 mm x 1.4 mm body

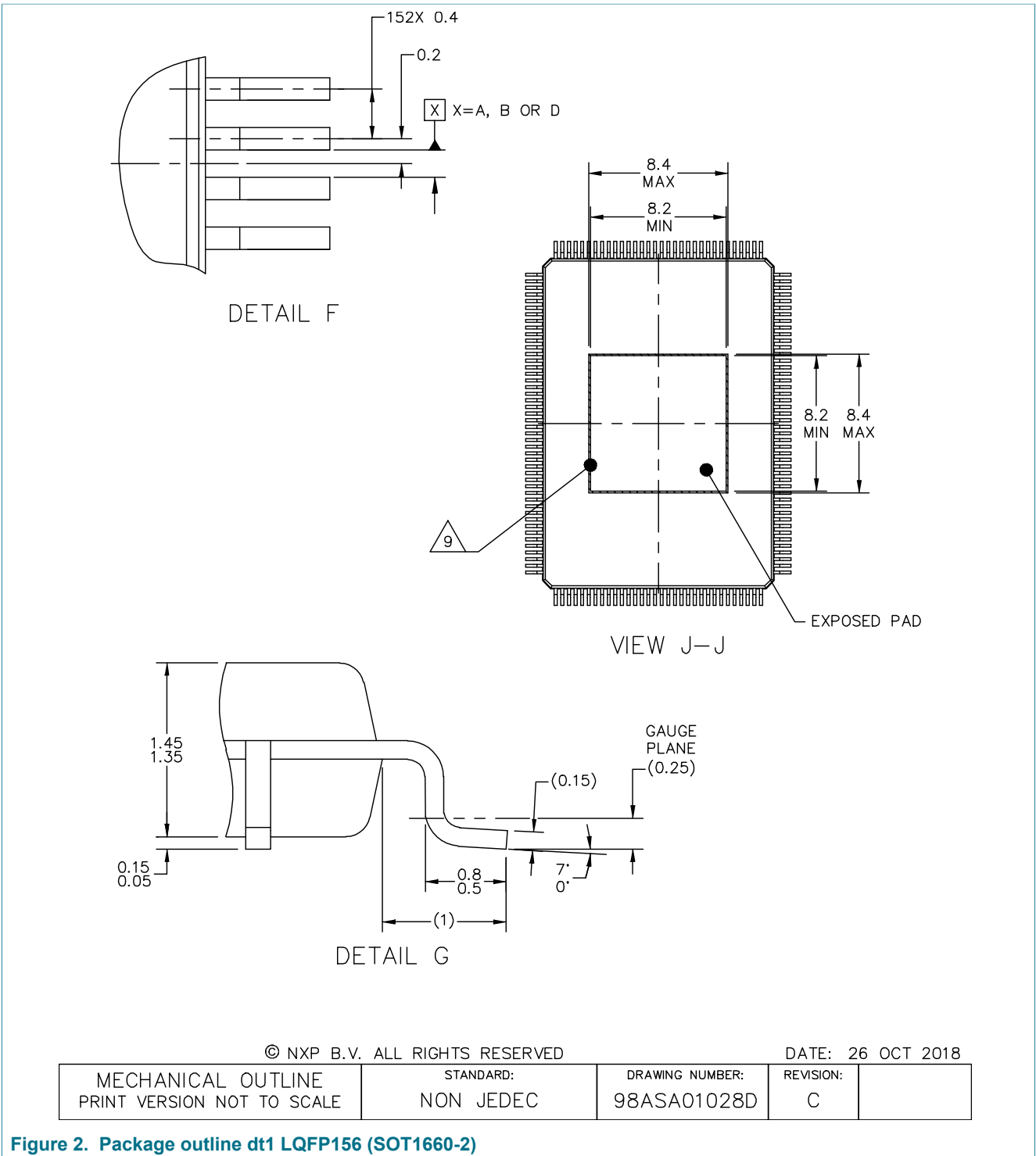


Figure 2. Package outline dt1 LQFP156 (SOT1660-2)

3 Soldering

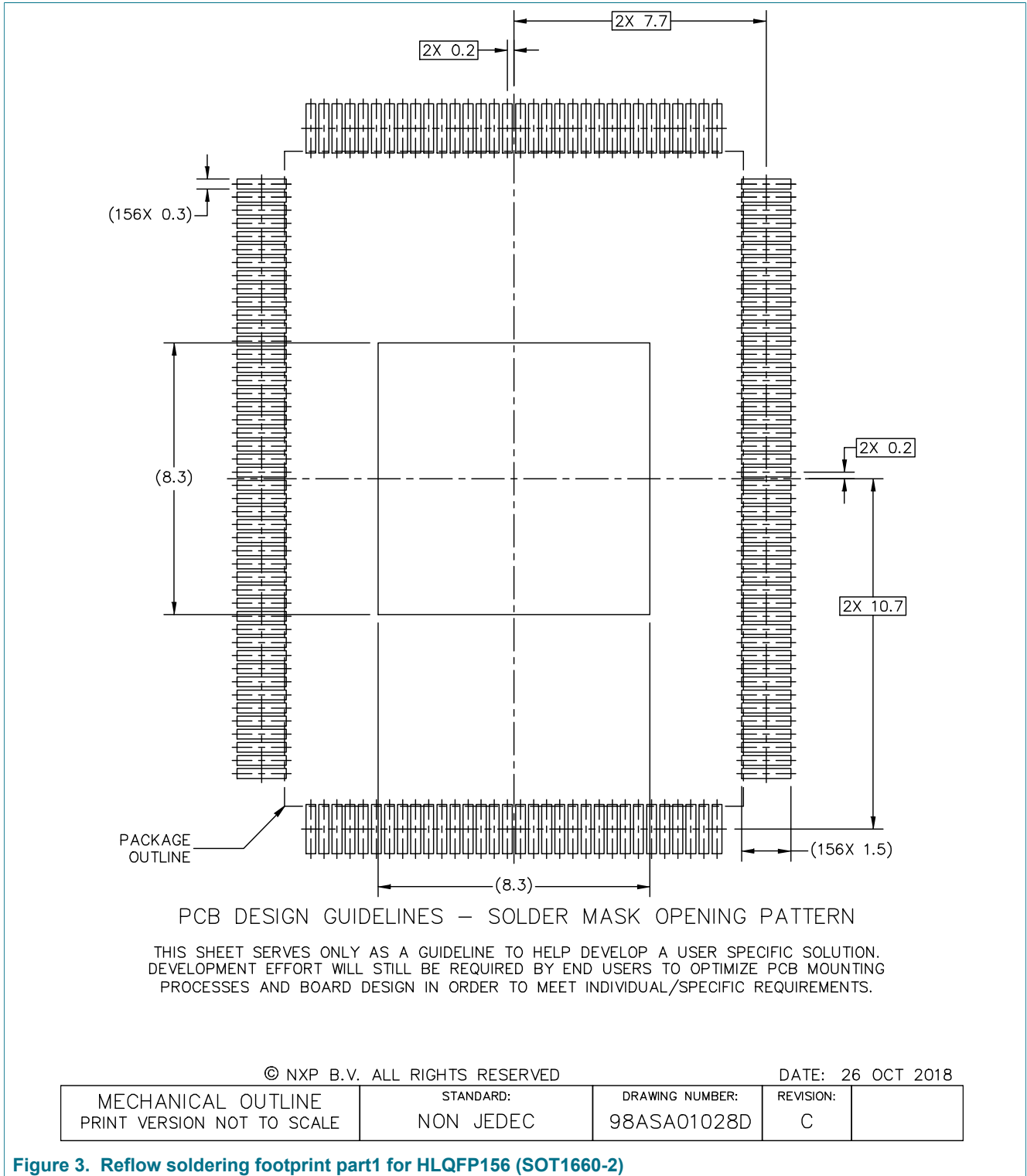


Figure 3. Reflow soldering footprint part1 for HLQFP156 (SOT1660-2)

HLQFP156, plastic, thermal enhanced low profile quad flat package; 156 terminals; 0.4 mm pitch; 14 mm x 20 mm x 1.4 mm body

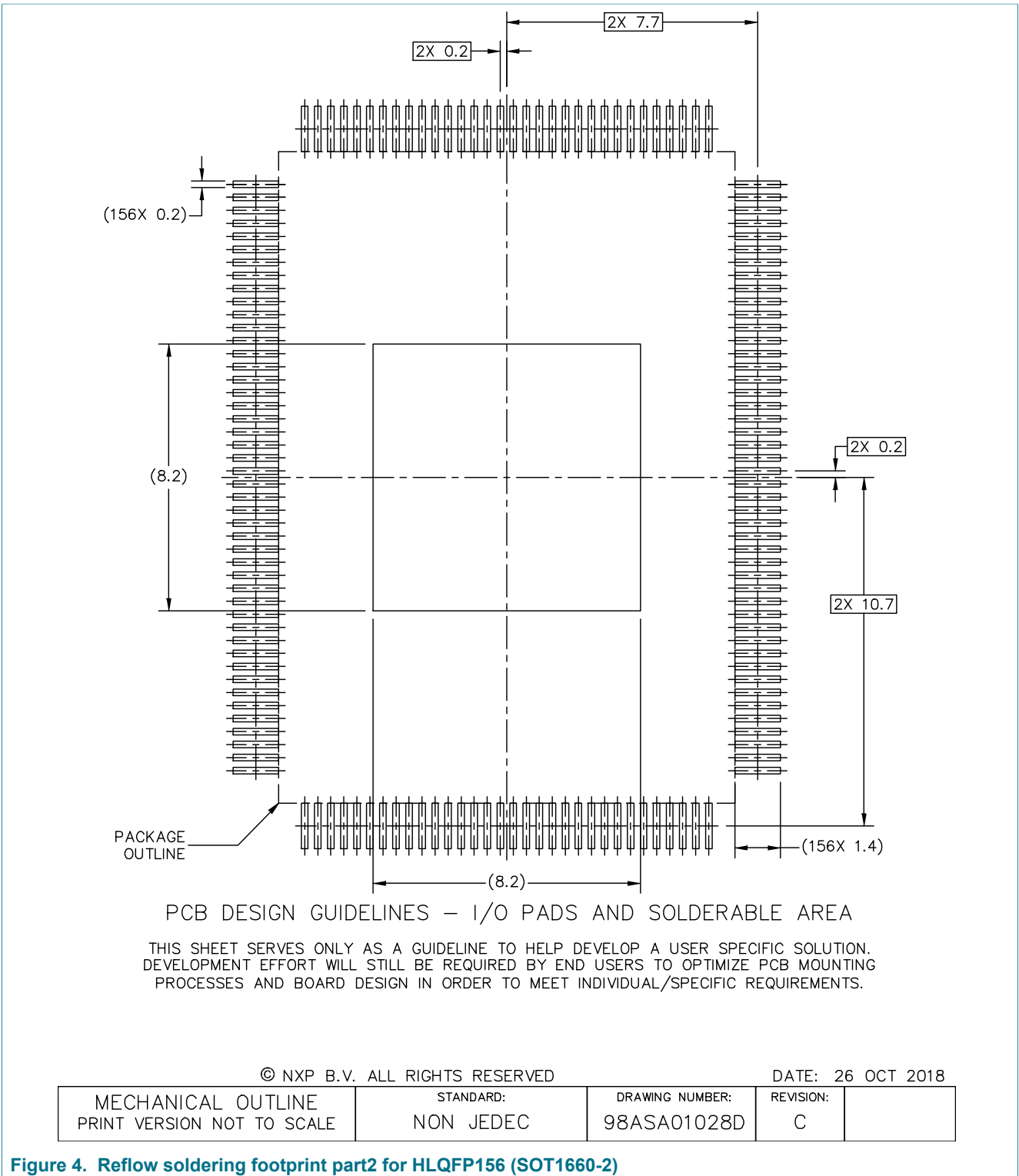


Figure 4. Reflow soldering footprint part2 for HLQFP156 (SOT1660-2)

HLQFP156, plastic, thermal enhanced low profile quad flat package; 156 terminals; 0.4 mm pitch; 14 mm x 20 mm x 1.4 mm body

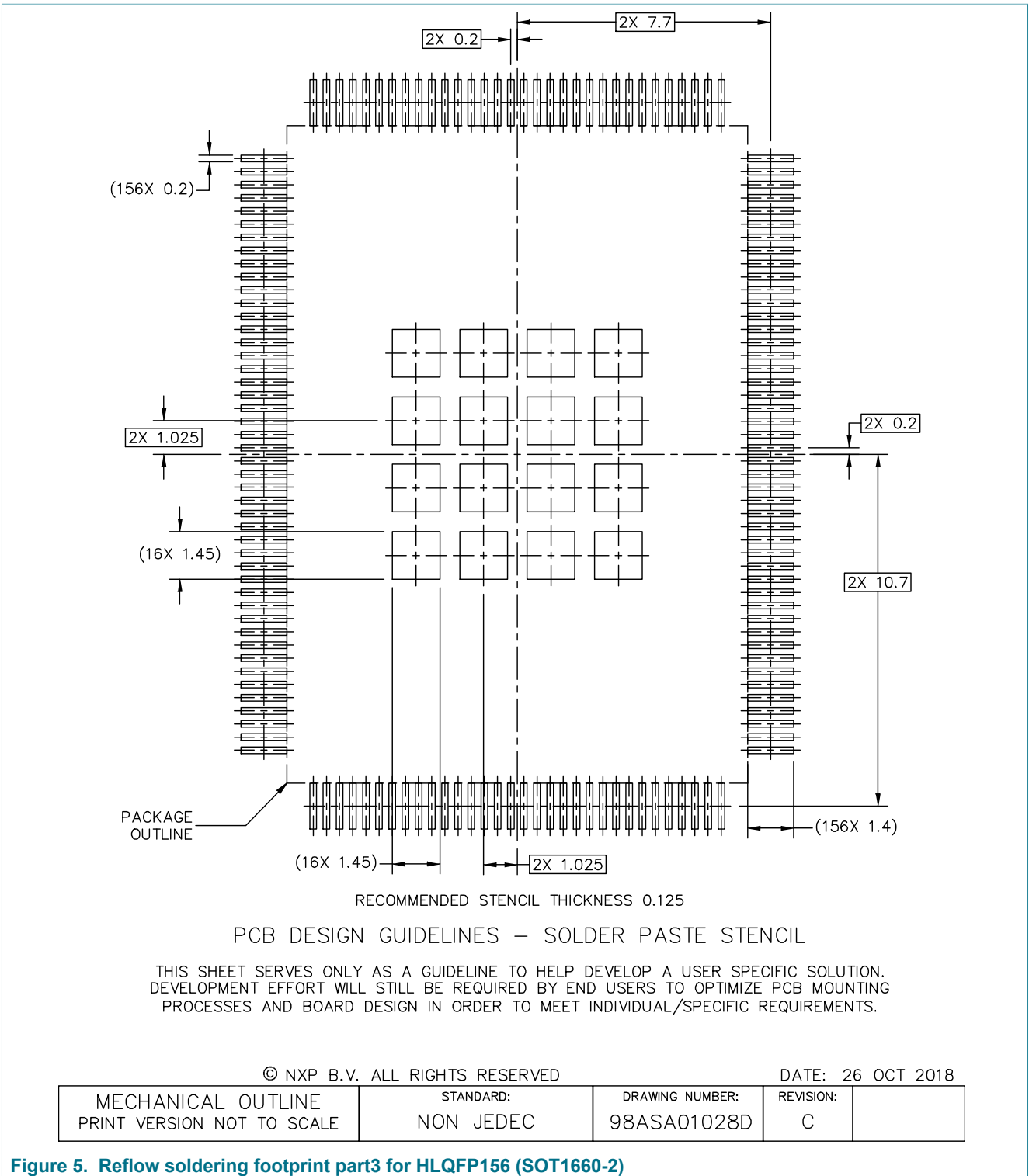


Figure 5. Reflow soldering footprint part3 for HLQFP156 (SOT1660-2)

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 CONFIGURATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 26 OCT 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01028D	REVISION: C	
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Figure 6. Package outline note LQFP156 (SOT1660-2)

4 Legal information

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